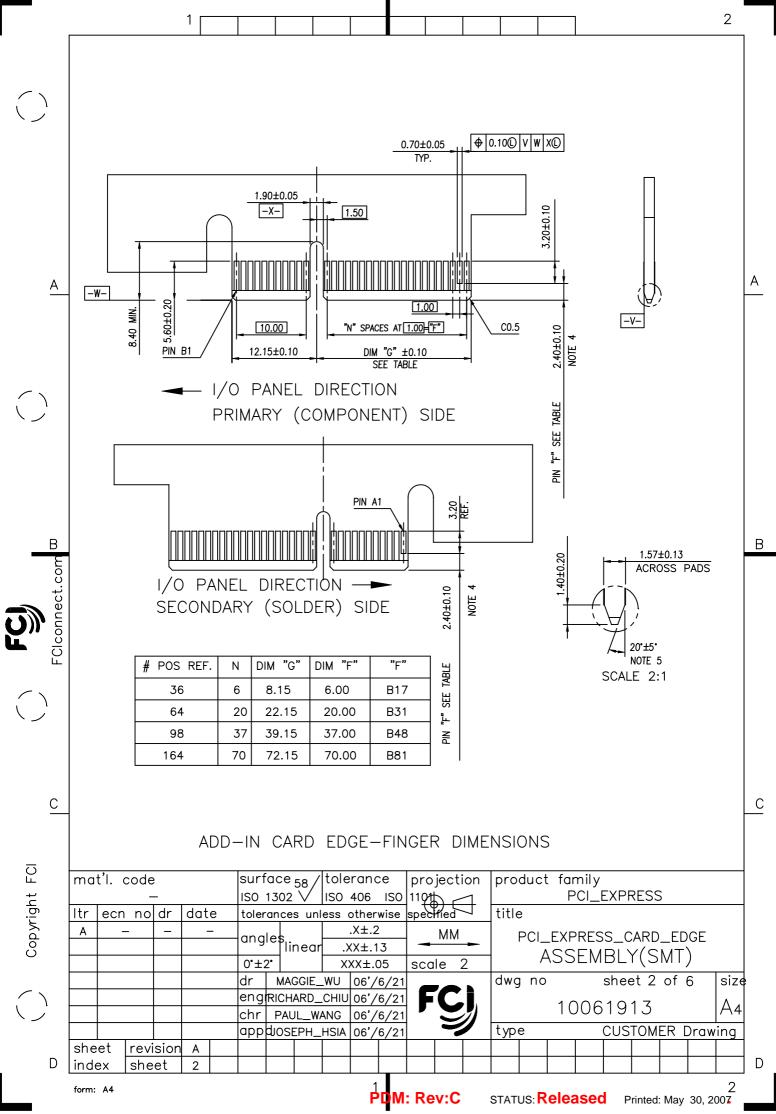


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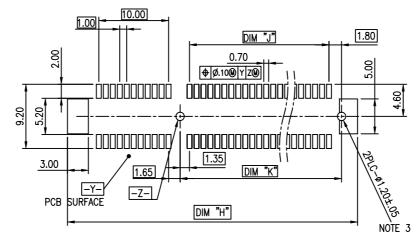
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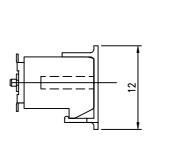


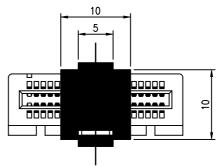


RECOMMENDED PCB LAYOUT, PAD TYPE

DIMENSIONS									
POSITION	Α	B ±0.15 -0.05	C ±0.20	D ±0.23	E ±0.20	H ±0.10	7	K ±0.10	
36	6.00	7.65	9.15	25.00	27.00	28.00	6.00	9.15	
64	20.00	21.65	23.15	39.00	41.00	42.00	20.00	23.15	
98	37.00	38.65	40.15	56.00	58.00	59.00	37.00	40.15	
164	70.00	71.65	73.15	89.00	91.00	92.00	70.00	73.15	

POSTION OF CAP





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mat'l. code		surface 58/		tolerance		pro	jecti	ion	product family													
_							1104		1		PCI_EXPRESS											
Itr	ecn	no dr	da	te	toler	ISO 1302 ✓ ISO 406 ISO tolerances unless otherwise s					spec	fled	<u> </u>	title								
Α	_			_	angles linear		.X±.2			ММ			PCI_EXPRESS_CARD_EDGE									
							.XX±.13		-		_		ASSEMBLY(SM									
					0°±2			XXX±.05		sca	le 2	2	ASSLINIDET (SINIT)									
					dr		GGIE_			[′] 6/21	_			dwg	j no			shee	et 3	of	6	size
					engrichard_chiu 06'/6/21			C	, [,	10061913 A4							٨٨					
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					app	dos	EPH_	HSIA	06'/	6/21				typ	е			CUS	TOM	ER [Draw	ing
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inde	ex s	sheet	3																			

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Α

В

1.MATERIAL:

HOUSING: NYLON, GLASS FILLED UL94V-O RATE, SUITABLE FOR I.R SOLDERING.

TERMINAL: COPPER ALLOY

PLATING: 50u" NICKEL UNDERPLATE ALL OVER

CONTACT AREA PLATING — SEE PRODUCT NUMBER CODE SOLDER TAIL: TIN 100u" OVER 50u" NICKEL

METAL PADS: COPPER ALLOY FINISH: 100u" TIN OVER 50u" NICKEL 2.PRODUCT SPECIFICATION: GS-12-390

3THE HORIZONTAL AXIS FOR THE PAD PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø1.0 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER

OF DATUM -Z-

(4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1.

(5) CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- PLATING:

"LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 5 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

PRODUCT NUMBER CODE

10061913-xxxxLF

HOUSING COLOR OPTIONS

1-BLACK

LEAD FREE

PACKAGING OPTIONS

-TRAY PACKAGING WITHOUT CAP -TAPE & REEL PACKING WITHOUT CAP (FOR 36P&64P OPTIONS ONLY)

-TAPE & REEL PACKING WITH CAP (FOR 36P&64P OPTIONS

C-TRAY PACKAGING WITH CAP (FOR 36,64,98P OPTIONS ONLY)

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE 30u" Au CONTACT AREA 100u" TIN TAIL AREA ----- COMPATIBLE RoHS

–50u" Ni UNDERPLATE 15u" Au CONTACT AREA 100u" TIN TAIL AREA –-

-- COMPATIBLE RoHS

2-50u" Ni UNDERPLATE

GOLD FLASH CONTACT AREA 100u" TIN TAIL AREA ---- COMPATIBLE RO

POS OPTIONS

0 - 361 - 64

2 - 98

3 - 164

HS		

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surface ₅₈ mat'l. code /tolerance projection product family 1101 specified PCI_EXPRESS ISO 406 ISO ISO 1302 \ title date ltr ecn no dr tolerances unless otherwise angle\$ linear MM PCI_EXPRESS_CARD_EDGE .XX±.13 ASSEMBLY(SMT) 0°±2° XXX±.05 scale sheet4 of 6 size MAGGIE_WU | 06'/6/21 dwg no eng|RICHARD_CHIU|06'/6/21 10061913 PAUL_WANG chr 06'/6/21 CUSTOMER Drawing appbloseph_HSIA 06'/6/21 type sheet revision index sheet

form: A4

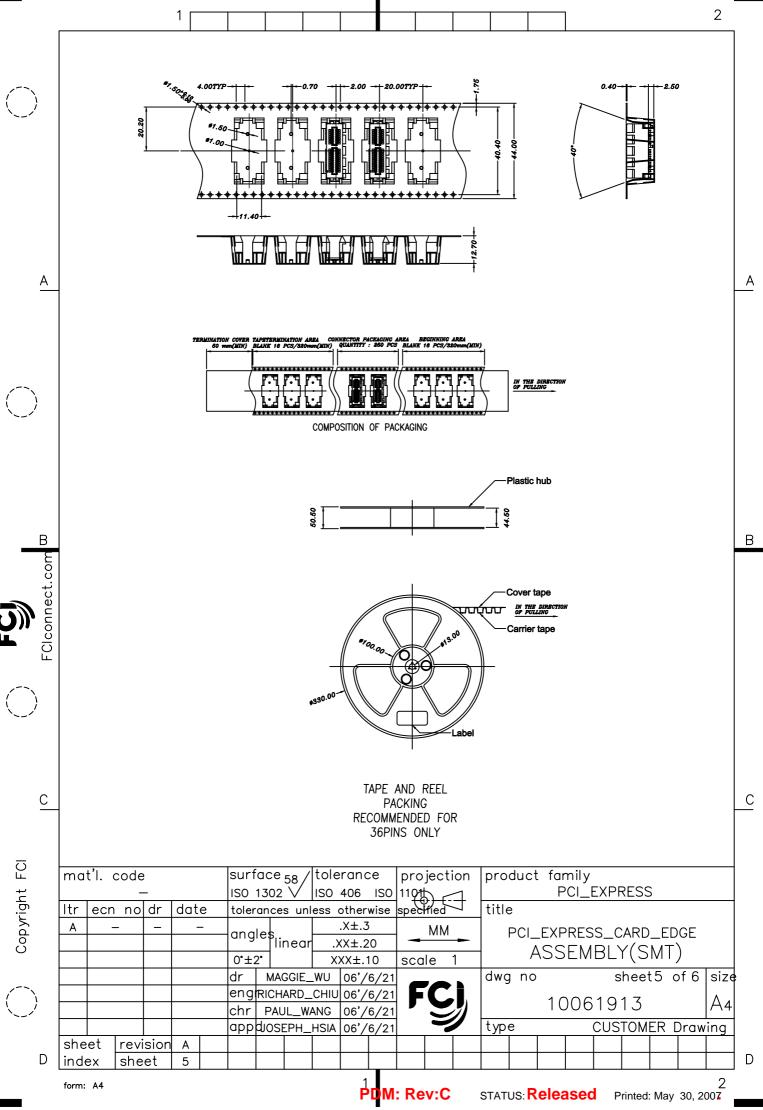
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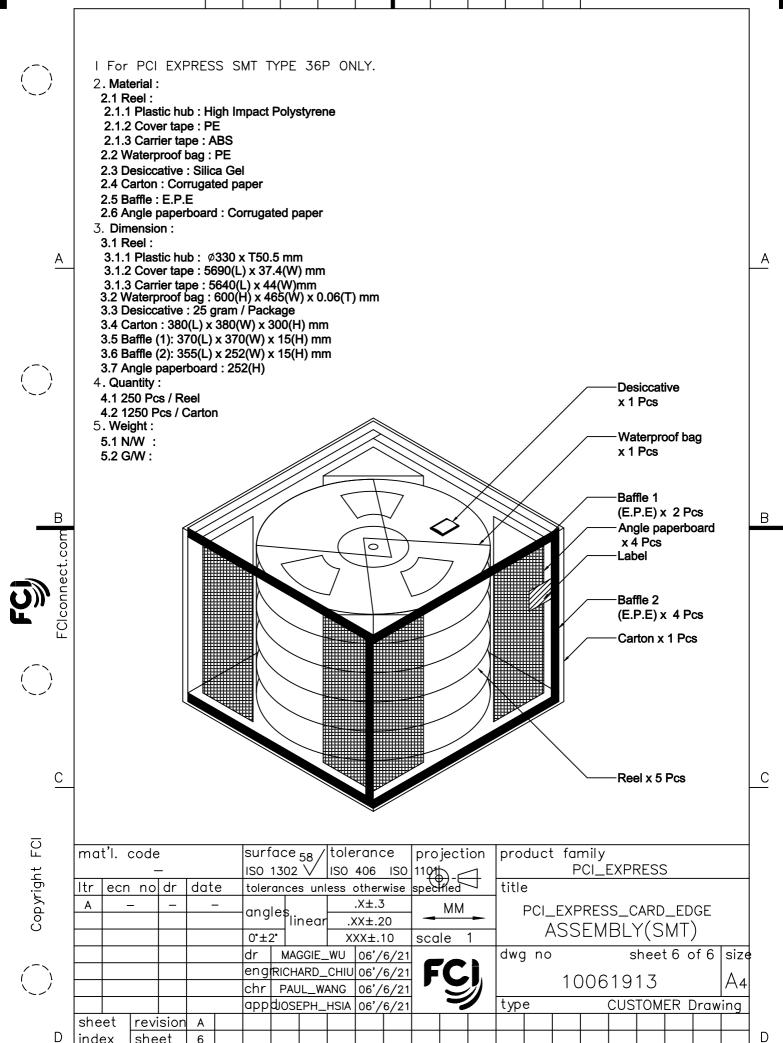
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